

□ MN103SB9 Series

Type	MN103SB9N	MN103SFB9R
Internal ROM type	Mask ROM	FLASH
ROM (byte)	512K	1024K
RAM (byte)	32K	
Package (Lead-free)	TQFP128-P-1414A	
Minimum Instruction Execution Time	16.7 ns (at 2.7 V to 3.6 V, 60 MHz)	

■ Interrupts

RESET. IRQ × 9. NMI. Timer × 28. I²C × 3. SIF × 10. DMA × 12. WDT. A/D. Time base timer × 2. System error

■ Timer Counter

8-bit timer × 10

Reload-down count. Cascade connection possible (usable as a 16-bit to 32-bit timer)

16-bit timer × 6

Up-down count. Input capture. PWM output. Compare/capture register 2 channels

Time base timer × 1

Watchdog timer × 1

■ Serial interface

UART/Synchronous/Multi-master I²C interface selective × 3

UART/Synchronous interface selective × 2

■ DMA controller

Number of channels: 4 channels

Unit of transfer: 8/16/32 bits

Maximum transfer cycles: 65535

Starting factor: External interrupt. Timer. Serial transmission/reception. A/D conversion finish. I²C transmission/reception. External transmission request. Software

Transfer method: 2-bus cycle transfer

Addressing modes: Fixed. Increment. Decrement

Transfer mode: Word transfer. Burst transfer. Intermittent transfer

■ Extended Calculation

Multiply and accumulate arithmetic. Multiplication. Saturated arithmetic

■ I/O Pins

I/O 104 : Common use

■ A/D converter

10-bit × 12 channels

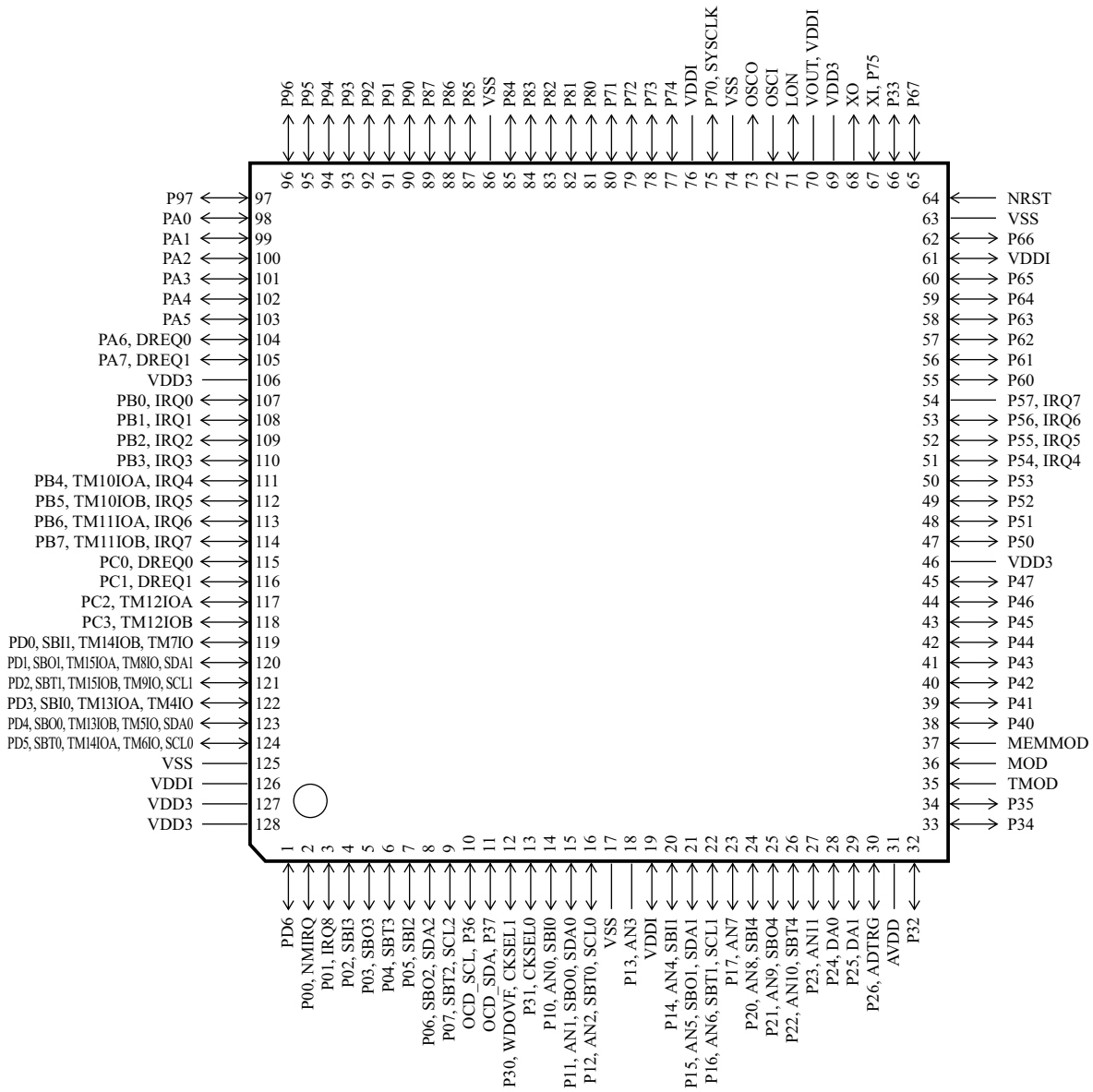
■ ROM Correction

8 channels

■ Electrical Characteristics (A/D converter characteristics)

Parameter	Symbol	Condition	Limit			Unit
			min	typ	max	
Resolution					10	Bits
Non-linear error		AVDD = 3.3 V. VSS = 0 V			±4	LSB
Differential non-linearity error					±4	LSB

■ Pin Assignment
TQFP128-P-1414A



Request for your special attention and precautions in using the technical information and semiconductors described in this book

- (1) If any of the products or technical information described in this book is to be exported or provided to non-residents, the laws and regulations of the exporting country, especially, those with regard to security export control, must be observed.
- (2) The technical information described in this book is intended only to show the main characteristics and application circuit examples of the products. No license is granted in and to any intellectual property right or other right owned by Panasonic Corporation or any other company. Therefore, no responsibility is assumed by our company as to the infringement upon any such right owned by any other company which may arise as a result of the use of technical information described in this book.
- (3) The products described in this book are intended to be used for standard applications or general electronic equipment (such as office equipment, communications equipment, measuring instruments and household appliances).
Consult our sales staff in advance for information on the following applications:
 - Special applications (such as for airplanes, aerospace, automobiles, traffic control equipment, combustion equipment, life support systems and safety devices) in which exceptional quality and reliability are required, or if the failure or malfunction of the products may directly jeopardize life or harm the human body.
 - Any applications other than the standard applications intended.
- (4) The products and product specifications described in this book are subject to change without notice for modification and/or improvement. At the final stage of your design, purchasing, or use of the products, therefore, ask for the most up-to-date Product Standards in advance to make sure that the latest specifications satisfy your requirements.
- (5) When designing your equipment, comply with the range of absolute maximum rating and the guaranteed operating conditions (operating power supply voltage and operating environment etc.). Especially, please be careful not to exceed the range of absolute maximum rating on the transient state, such as power-on, power-off and mode-switching. Otherwise, we will not be liable for any defect which may arise later in your equipment.
 - Even when the products are used within the guaranteed values, take into the consideration of incidence of break down and failure mode, possible to occur to semiconductor products. Measures on the systems such as redundant design, arresting the spread of fire or preventing glitch are recommended in order to prevent physical injury, fire, social damages, for example, by using the products.
- (6) Comply with the instructions for use in order to prevent breakdown and characteristics change due to external factors (ESD, EOS, thermal stress and mechanical stress) at the time of handling, mounting or at customer's process. When using products for which damp-proof packing is required, satisfy the conditions, such as shelf life and the elapsed time since first opening the packages.
- (7) This book may be not reprinted or reproduced whether wholly or partially, without the prior written permission of our company.